

**APPLICATIONS**

- Inverse, Parallel Or Series Connected Diode
- Power Supplies
- High Frequency Applications

**FEATURES**

- Glass Passivation
- High Voltage Capability
- Fast Recovery Characteristics

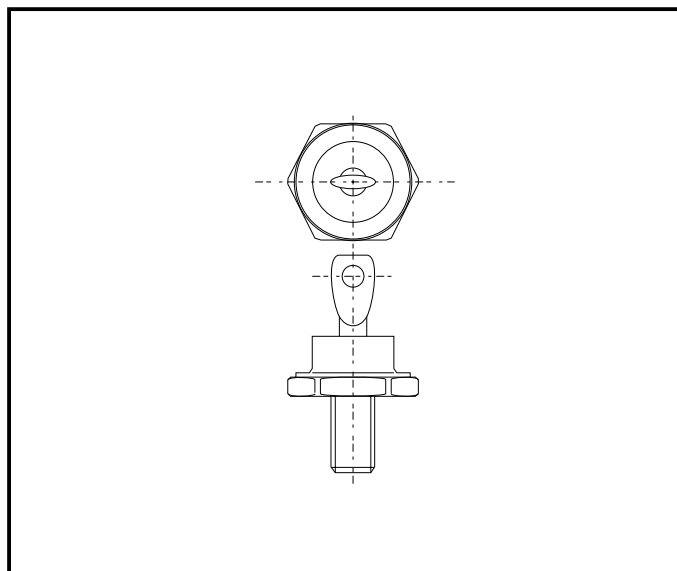
**KEY PARAMETERS**

$V_{RRM}$	<b>1200V</b>
$I_{F(AV)}$	<b>40A</b>
$I_{FSM}$	<b>400A</b>
$Q_r$	<b>10<math>\mu</math>C</b>
$t_{rr}$	<b>0.2ns</b>

**VOLTAGE RATINGS**

Type Number	Repetitive Peak Reverse Voltage $V_{RRM}$ V	Conditions
MF35 - 1200	1200	$V_{RSM} = V_{RRM} + 100V$
MF35 - 1000	1000	
MF35 - 800	800	
MF35 - 600	600	

Lower voltage grades available.  
For stud anode add suffix 'R' to type number. e.g. MF35-1200R.



Outline type code: DO5.  
See Package Details for further information.

**CURRENT RATINGS**

Symbol	Parameter	Conditions	Max.	Units
$I_{F(AV)}$	Mean forward current	Half sine wave resistive load, $T_{case} = 65^{\circ}C$	40	A
$I_{F(RMS)}$	RMS value	$T_{case} = 65^{\circ}C$	63	A
$I_F$	Continuous (direct) forward current	$T_{case} = 65^{\circ}C$	50	A

## MF35

### SURGE RATINGS

Symbol	Parameter	Conditions	Max.	Units
$I_{FSM}$	Surge (non-repetitive) forward current	10ms half sine; with $V_{RRM} \leq 10V$ , $T_j = 125^\circ C$	400	A
$I^2t$	$I^2t$ for fusing	10ms half sine; $T_j = 125^\circ C$	800	A <sup>2</sup> s

### THERMAL AND MECHANICAL DATA

Symbol	Parameter	Conditions	Min.	Max.	Units
$R_{th(j-c)}$	Thermal resistance - junction to case	dc	-	0.8	°C/W
$R_{th(c-h)}$	Thermal resistance - case to heatsink	Mounting torque 3.5Nm with mounting compound	-	0.2	°C/W
$T_{vj}$	Virtual junction temperature	Forward (conducting)	-	125	°C
		Reverse (blocking)	-	125	°C
$T_{stg}$	Storage temperature range		-55	125	°C
-	Mounting torque		3.2	3.8	Nm

### CHARACTERISTICS

Symbol	Parameter	Conditions	Typ.	Max.	Units
$V_{FM}$	Forward voltage	At 120A peak, $T_{case} = 25^\circ C$	-	2.0	V
$I_{RM}$	Peak reverse current	At $V_{RRM}$ , $T_{case} = 100^\circ C$	-	5	mA
$t_{rr}$	Reverse recovery time	$I_F = 1A$ , $di_{RR}/dt = 25A/\mu s$ , $T_{case} = 25^\circ C$ , $V_R = 100V$	-	200	ns
$Q_R$	Recovered charge	$I_F = 50A$ , $di_{RR}/dt = 50A/\mu s$ , $T_{case} = 25^\circ C$ , $V_R = 100V$	-	10	$\mu C$
$V_{TO}$	Threshold voltage	At $T_{vj} = 125^\circ C$	-	1.2	V
$r_T$	Slope resistance	At $T_{vj} = 125^\circ C$	-	7.0	m $\Omega$

CURVES

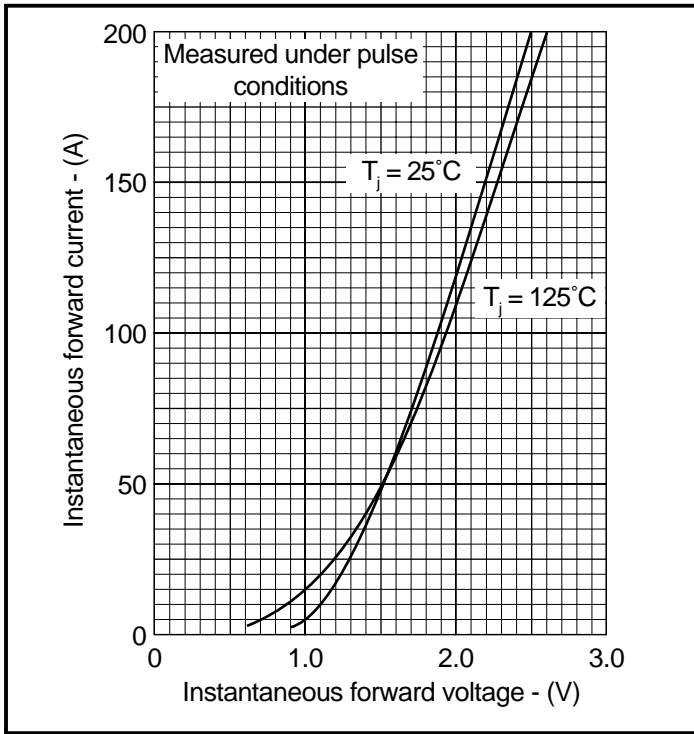


Fig.1 Maximum (limit) forward characteristics

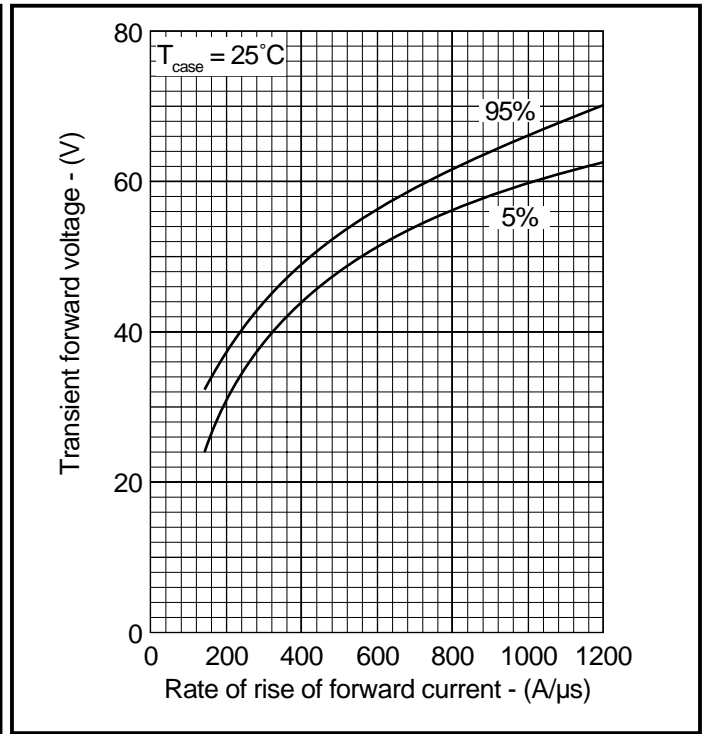


Fig.2 Forward recovery voltage vs rate of rise of forward voltage

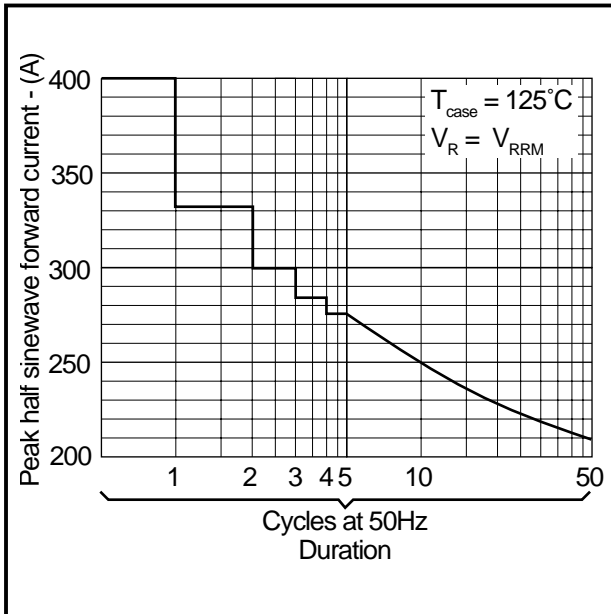


Fig.3 Surge (non-repetitive) forward current vs time

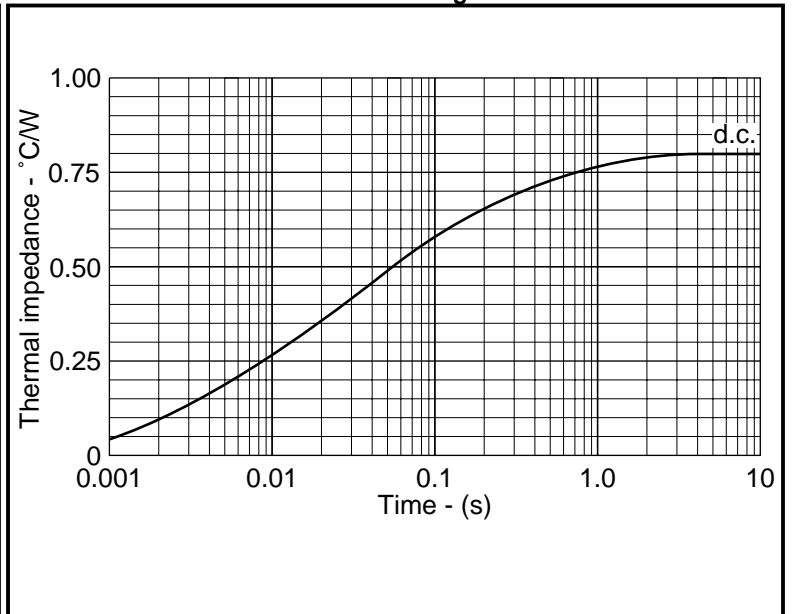


Fig.4 Maximum transient thermal impedance

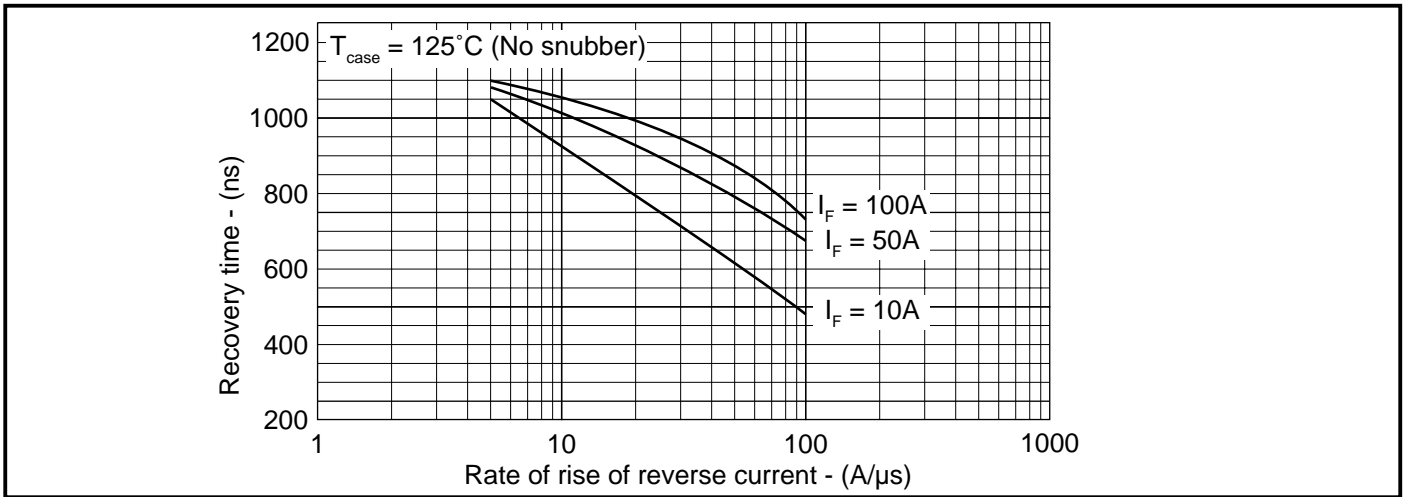


Fig.5 Recovery time vs  $di_R/dt$

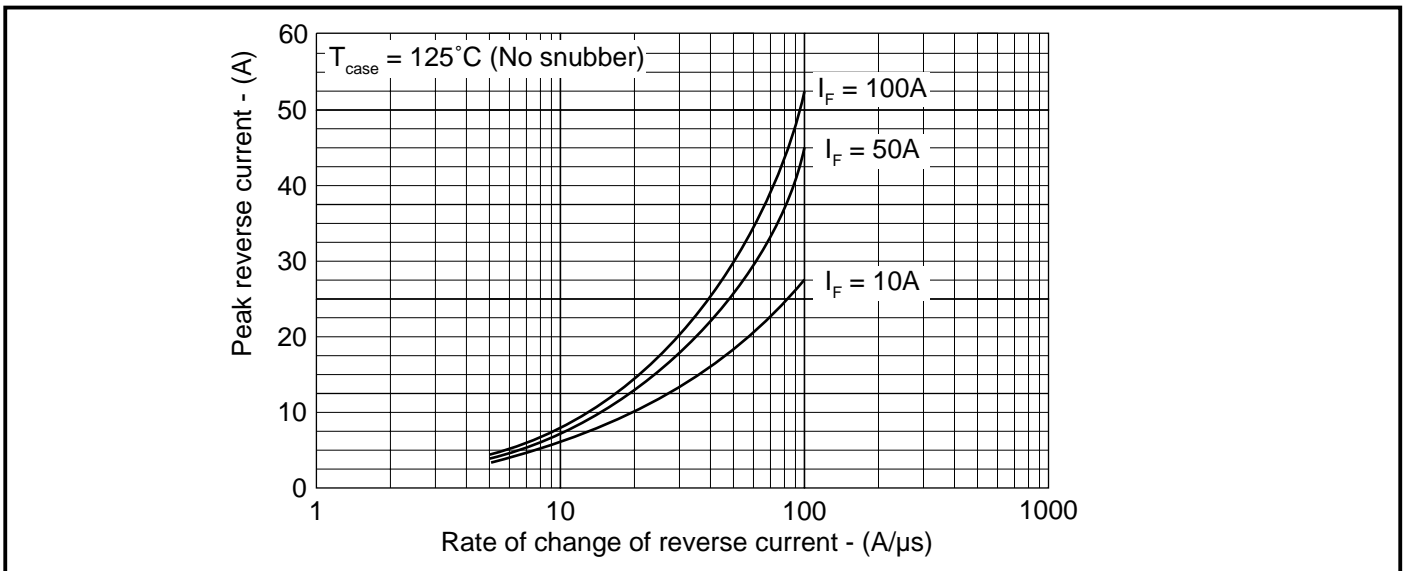


Fig.6 Peak reverse current vs  $di_R/dt$

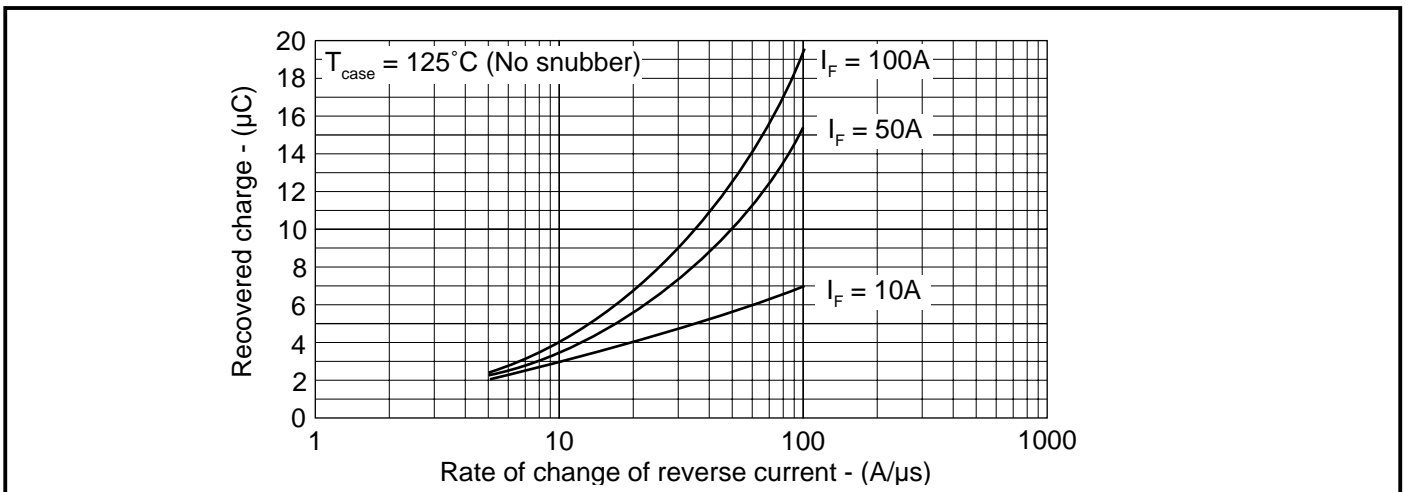


Fig.7 Recovered charge vs  $di_R/dt$

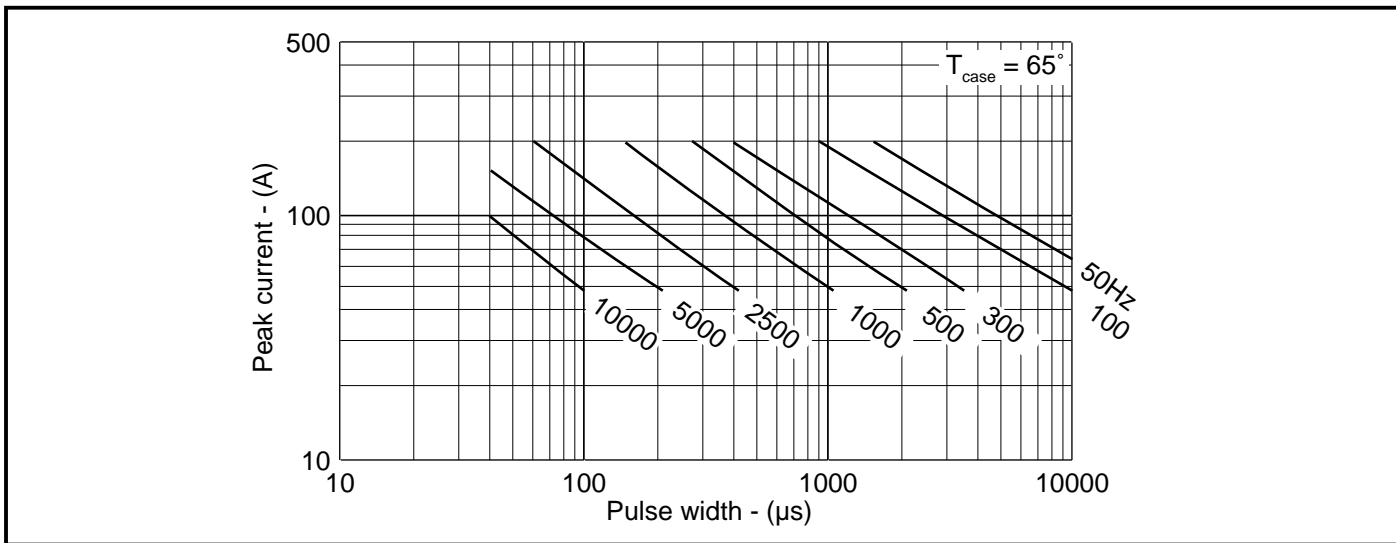


Fig.8 Frequency curves - square waveform

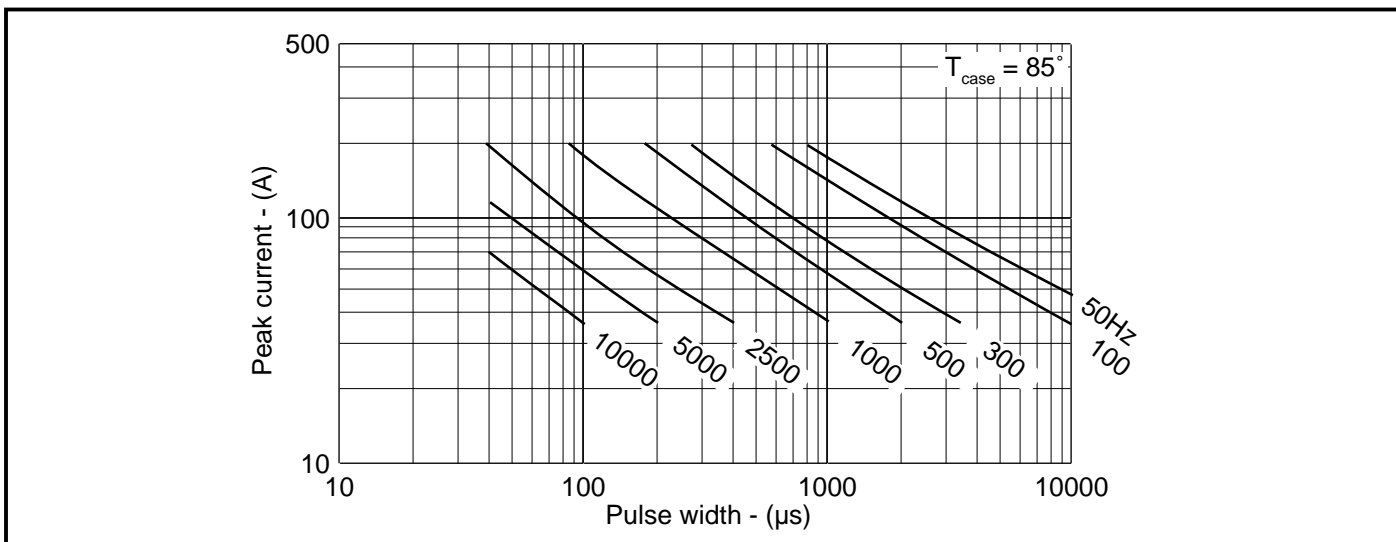


Fig.9 Frequency curves - square waveform

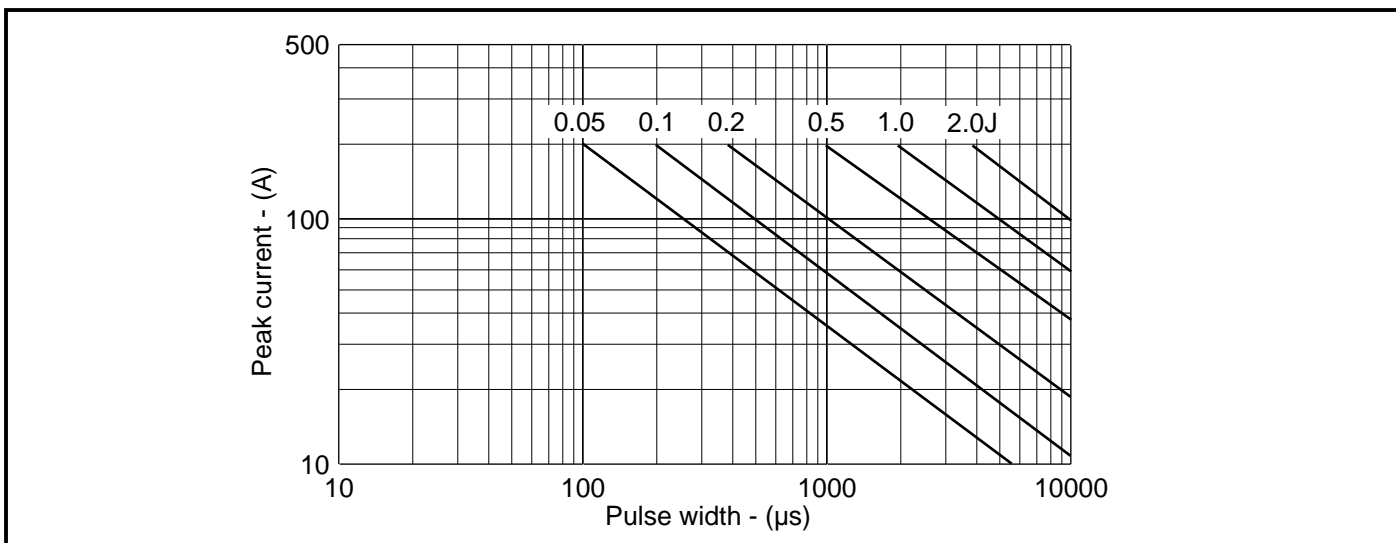


Fig.10 Energy per pulse - square waveform

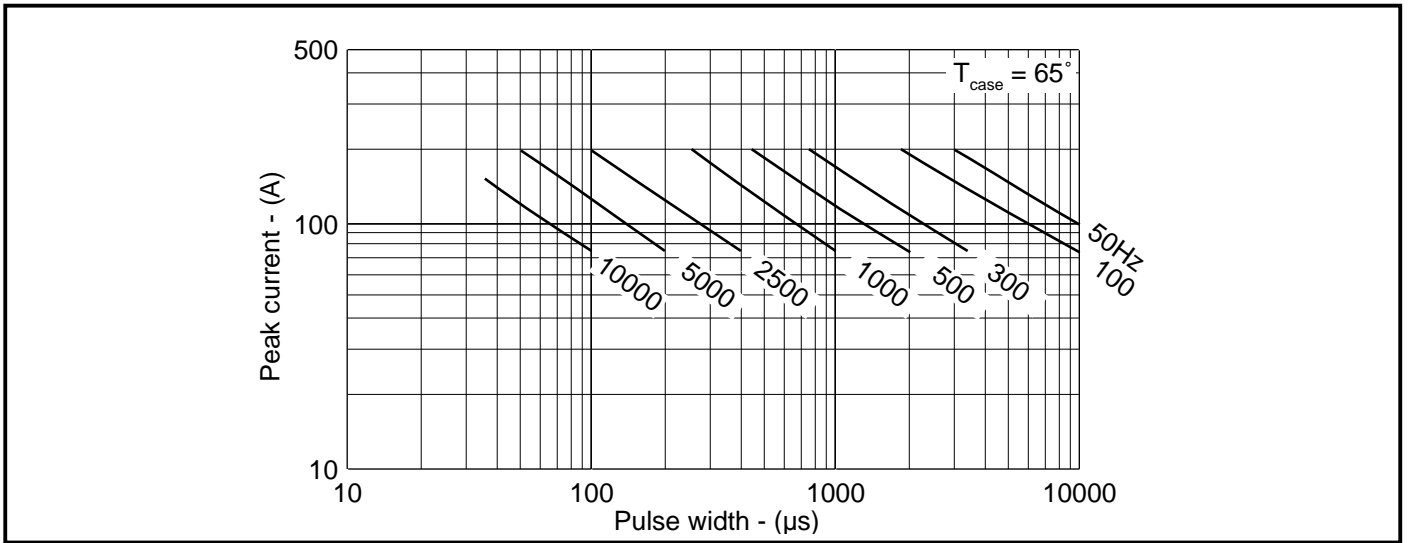


Fig.11 Frequency curves - sine waveform

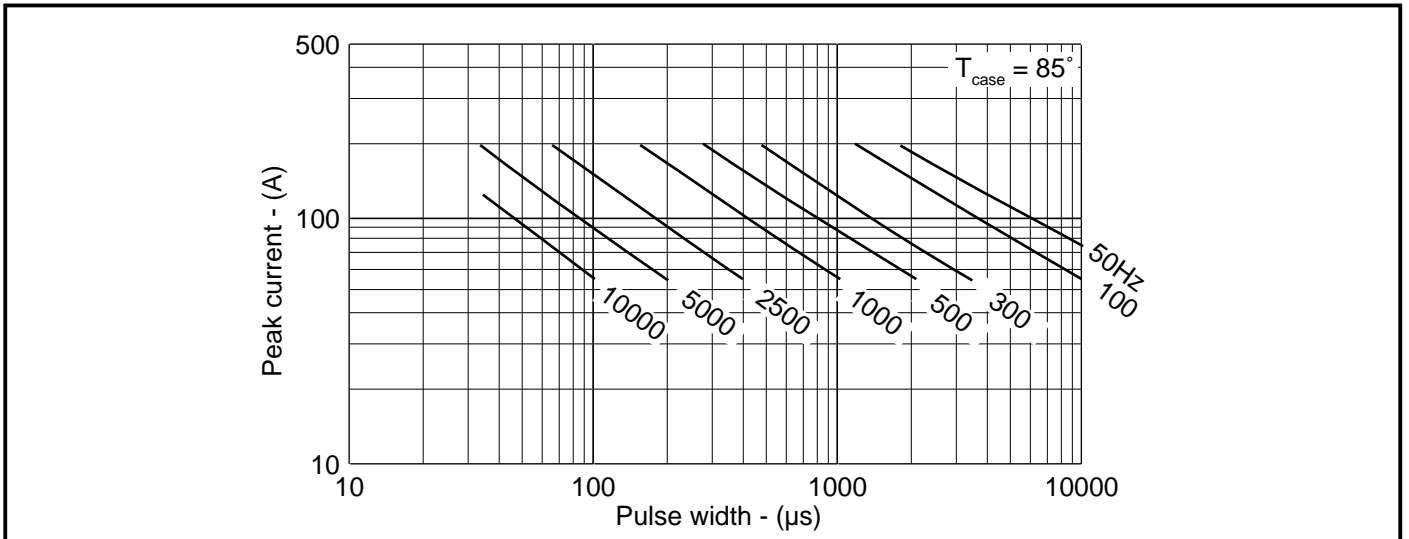


Fig.12 Frequency curves - sine waveform

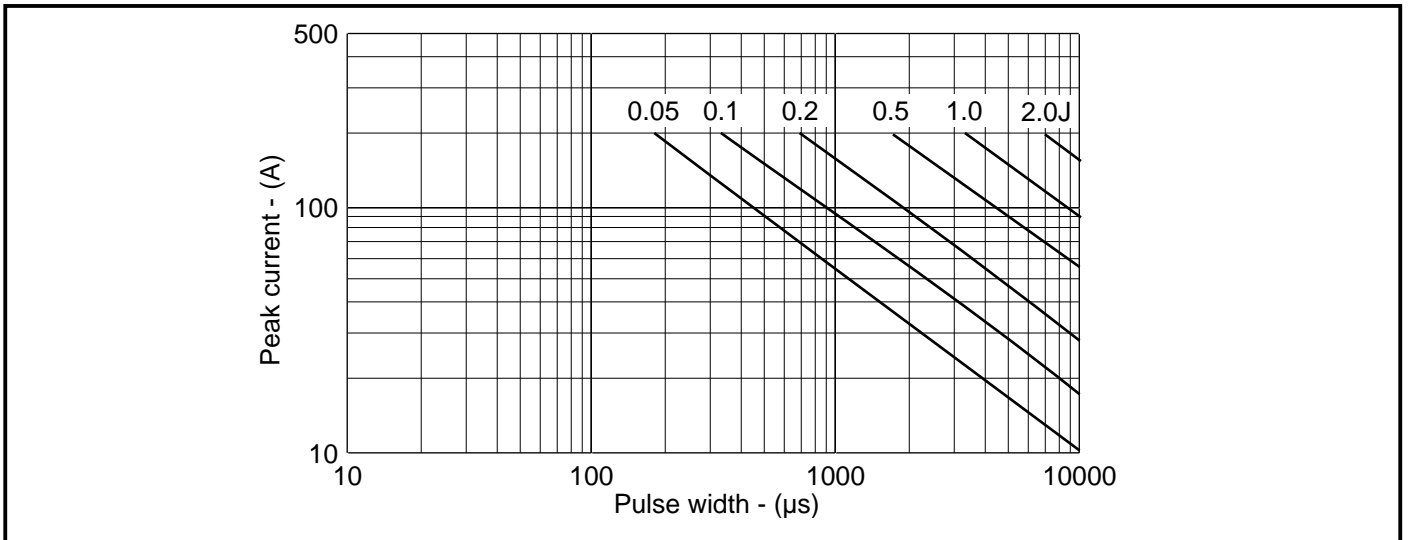
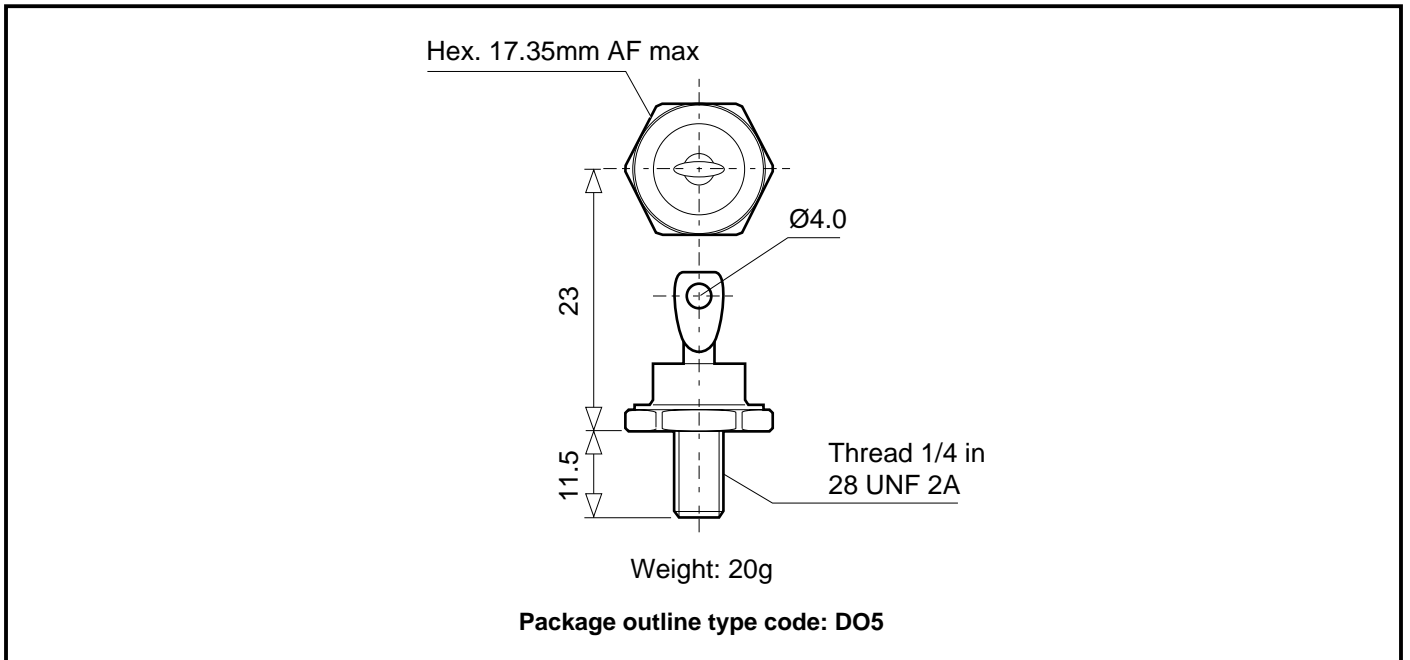


Fig.13 Energy per pulse - sine waveform

**PACKAGE DETAILS**

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise.  
DO NOT SCALE.



## POWER ASSEMBLY CAPABILITY

The Power Assembly group was set up to provide a support service for those customers requiring more than the basic semiconductor, and has developed a flexible range of heatsink and clamping systems in line with advances in device voltages and current capability of our semiconductors.

We offer an extensive range of air and liquid cooled assemblies covering the full range of circuit designs in general use today. The Assembly group offers high quality engineering support dedicated to designing new units to satisfy the growing needs of our customers.

Using the latest CAD methods our team of design and applications engineers aim to provide the Power Assembly Complete Solution (PACs).

## HEATSINKS

The Power Assembly group has its own proprietary range of extruded aluminium heatsinks which have been designed to optimise the performance of Dynex semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest sales representative or Customer Services.



<http://www.dynexsemi.com>

**e-mail: [power\\_solutions@dynexsemi.com](mailto:power_solutions@dynexsemi.com)**

HEADQUARTERS OPERATIONS  
**DYNEX SEMICONDUCTOR LTD**  
Doddington Road, Lincoln.  
Lincolnshire. LN6 3LF. United Kingdom.  
Tel: +44-(0)1522-500500  
Fax: +44-(0)1522-500550

CUSTOMER SERVICE  
Tel: +44 (0)1522 502753 / 502901. Fax: +44 (0)1522 500020

SALES OFFICES  
**Benelux, Italy & Switzerland:** Tel: +33 (0)1 64 66 42 17. Fax: +33 (0)1 64 66 42 19.  
**France:** Tel: +33 (0)2 47 55 75 52. Fax: +33 (0)2 47 55 75 59.  
**Germany, Northern Europe, Spain & Rest Of World:** Tel: +44 (0)1522 502753 / 502901.  
Fax: +44 (0)1522 500020  
**North America:** Tel: (613) 723-7035. Fax: (613) 723-1518. Toll Free: 1.888.33.DYNEX (39639) /  
Tel: (949) 733-3005. Fax: (949) 733-2986.

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**Preliminary Information:** The product is in design and development. The datasheet represents the product as it is understood but details may change.

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